

## TRANSISTOR WITH $\pi$ -GATE STRUCTURE AND METHOD FOR PRODUCING THE SAME

### FIELD OF THE INVENTION

The present invention relates to a transistor with  $\pi$  -gate structure usable at microwave and millimeter wave and a method for producing the same.

### BACKGROUND OF THE INVENTION

Conventional extra-high speed transistors were manufactured to have T-gate structure in order to increase the cross section of gates. However, there was a limit in increasing the cross section under the restriction of source-drain spacing. However, the present inventors found that the production of gates with very large cross section without the restriction of the source-drain spacing is possible, by employing an air bridge technique in which the gate is manufactured beyond the drain electrode to result in  $\pi$  -structure, whereby the characteristic of the transistor is remarkably improved.

### SUMMARY OF THE INVENTION

The present invention proposes the structure of a transistor having a gate of very large cross section and a method for manufacturing the same and so the object of the invention is to improve the noise factor and frequency characteristic of a circuit by decreasing the gate resistance in the transistors for microwave and millimeter wave.

The invention is also intended to improve the performance of a wireless communications system through the improvement in the characteristics of unit elements and circuits.

### BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 shows the sequential procedure of manufacturing a transistor according to the invention and

Figure 2 shows the so manufactured transistor according to the invention.

## DETAILED DESCRIPTION OF THE INVENTION

A preferred embodiment of the method for manufacturing a transistor with  $\pi$ -gate structure and a transistor so produced according to the invention is described in detail by referring to the accompanying drawings.

In a transistor shown in Figure 2, it is seen that a GaAs wafer 2 is formed on the bottom with GND 1, which is grounded to source layers 3 formed on the top surface of the GaAs wafer 2 by the process of back side via-hole 10. Between the source layers 3 there is formed a drain 5, the top part of which has an air layer 6. As the result of using the air bridge technique, a gate 4 is shaped such that it contacts the top surface of the GaAs wafer 2 between the source layers 3 and the drain 5 and so supports both sides of the wafer over the opening or air layer 6 of the drain 5, resulting in a gate having  $\pi$ -structure.

The manufacturing method of gate with  $\pi$ -structure by using an air bridge technique comprises:

the step of vapor-depositing, on a wafer 2, to form a drain 5 and source layers 3 of Ti/Au as the primary metal layers in the thickness of 200 Å/4000 Å through PHEMT process;

the step of forming silicon nitride film 9 in the thickness of 1000 Å, patterning the formed silicon nitride film 9 by using an electron beam exposure device, forming gate foot steps by etching the film, and then conducting HMDS coating by PR-via pattern forming process using the positive photo irradiation drawing process, conducting AZ1518 coating at 2000 rpm for 20 seconds, conducting soft-baking at 98°C for 45 seconds, aligning patterns, conducting UV exposure and developing for 1 minute and 30 seconds, and subsequently conducting a hard-baking at 115°C for 4 minutes and 30 seconds to thereby harden the resist 7;

the step of forming, by vapor-depositing, a thin gold film 8 in the thickness of

about 250~300 Å on the surface of GaAs wafer 2;

the step of conducting HMDS coating after forming secondary metal patterns 7a by using an image inversion process, conducting AZ5214E coating at 2000 rpm for 10 seconds, conducting soft-baking at 98°C for 45 seconds, aligning patterns, and then conducting free exposure for 7 seconds, reverse baking at 110°C for 50 seconds and plot exposure for 25 seconds before development;

the step of disconnecting the source 3 and drain 5 by etching off the exposed gold film 8 by using the metal etching solution consisting of N, KCN, H<sub>2</sub>O at the ratio of 10ml : 500ml : 100ml, and thereafter forming a gate 4 in the thickness of 200 Å /8000 Å by vapor deposition of Ti/Au and attaining a finished gate 4 with  $\pi$ -structure through lifting-off by means of acetone; and

the step of performing the process of back side via-hole 10 on the wafer 2 to ground the GND 1 to the source layer 3.

The process for manufacturing a transistor having  $\pi$ -gate structure is described in some more detail by referring to Figure 1:

As is shown in Figure 1A, a drain 5 and source layers 3 of Ti/Au as the primary metal layers are formed by vapor deposition in the thickness of 200 Å/4000 Å on a wafer 2 through PHEMT process. Subsequently, silicon nitride film 9 is laminated in the thickness of 1000 Å to form gate foot steps.

Then, as shown in Figure 1B, the laminated silicon nitride film 9 is patterned by using an electron beam exposure device before forming gate foot steps by etching the nitride film. Then, the PR-via pattern forming process using the positive photo irradiation drawing process is carried out, wherein after HMDS coating, AZ1518 coating is conducted at 2000 rpm for 20 seconds, and soft-baking at 98°C is subsequently conducted for 45 seconds, patterns are aligned, UV exposure and developing are performed for 1 minute and 30 seconds, and lastly a hard-baking at 115°C for 4 minutes and 30 seconds follows to thereby harden the resist 7.

As the next step, as in Figure 1C, by vapor-depositing, a thin gold film 8 is

formed in the thickness of about 250~300 Å on the surface of GaAs wafer 2 to prevent the resist 7 for PR-via from being developed at the time of patterning the secondary metal. At this time, the thickness of the thin gold film 8 is chosen to be minimum so as not to influence the process, because too large a thickness makes it difficult not only to align the patterns but also to lift off the bridge metal after it has been vapor-deposited, while too small a thickness even the portion of the resist 7 that should not be developed tends to be developed in the pattern forming process.

After having gone through the above steps, as shown in Figure 1D, the process of forming secondary metal patterns 7a by using an image inversion process is conducted, wherein after coating HMDS, AZ5214E coating is conducted at 2000 rpm for 10 seconds, soft-baking is conducted at 98°C for 45 seconds followed by pattern alignment, and then free exposure for 7 seconds, reverse baking at 110°C for 50 seconds and plot exposure for 25 seconds are sequentially performed before development;

In the next step as shown in Figure 1E in which a gate 4 is formed in the thickness of 200 Å/8000 Å by vapor deposition of Ti/Au, lifting-off by means of acetone has been conducted to form the air layer 6 so that the bridge manufacture is completed, the step of disconnecting the source 3 and drain 5 by etching off the exposed gold film 8 by using the metal etching solution consisting of N, KCN, H<sub>2</sub>O at the ratio of 10ml : 500ml : 100ml was conducted beforehand.

As the final step, the process of back side via-hole 10 is performed on the wafer 2 to ground the GND 1 to the source layer 3.

It is to be understood that, while the invention was described with respect to respective preferable specific embodiments, the invention is not restricted to those embodiments and a variety of modifications and alterations would be possible to a man skilled in the art by referring to the description or drawings presented here and within the spirit of the invention and thus those modifications or alterations are to fall within the scope of the invention, which scope should be limited only by the attached claims.